




APPROVED
status of the attached document
EXTERNAL ISSUE

Doc No.	SDSC-PSE-AN7164	Issue Level	Rev	Eff Date
		1	4	27-FEB-06
Doc Title	Product Specifications for AN7164	Total no. of pages (excluding this page)		8

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Prepared		Product Specifications AN7164	Ref No.	A-1
Checked			Total Page	8
Approved			Page No.	1

APPROVED
EXTERNAL ISSUE

Structure	Silicon Monolithic Bipolar IC
Appearance	FP12S Plastic Package (Power Type with Fin attached)
Application	Stereo Set • Karaoke • TV
Function	Low Frequency Power Amplifier




A Absolute Maximum Ratings					
No.	Item	Symbol	Ratings	Unit	Note
1	Storage Temperature	Tstg	-55 ~ +150	° C	1
2	Operating Ambient Temperature	Topr	-30 ~ +75	° C	1
3	Operating Ambient Pressure	Popr	$1.013 \times 10^5 \pm 0.61 \times 10^5$ (1.0 ± 0.6)	Pa (atm)	
4	Operating Constant Acceleration	Gopr	9,810 (1000)	m/s ² (G)	
5	Operating Shock	Sopr	4,900 (500)	m/s ² (G)	
6	Supply Voltage	Vcc	30	V	2
7	Supply Current	Icc	5.0	A	
8	Power Dissipation	P _D	62.5	W	$\theta_{j-c} = 2.0$ (°C/W)

Operating Supply Voltage Range	Vcc	8.3V ~ 24V
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Note 1) The temperature of all items shall be Ta=25°C except storage temperature and operating ambient temperature.

2) No signal.

Eff. Date	Eff. Date	Eff. Date	Eff. Date	
6-SEP-88	30-MAY-95	17-JUL-98		

Prepared		Product Specifications AN7164	<div> <div>APPROVED</div> <div>Ref No. B-1</div> <div>EXTERNAL ISSUE</div> </div>	
Checked			Total Page	8
Approved			Page No.	2

B Electrical Characteristics		(Unless otherwise specified, the ambient temperature is 25°C ± 2°C, Vcc=21V, RL=8Ω, freq=1kHz, BTL operation.)							
No	Item	Symbol	Test Circuit	Conditions	Limits			Unit	Note
					min	typ	max		
1	Quiescent Circuit Current	ICQ	1	Vin=0	-	55	100	mA	
2	Output Noise Voltage	Vno	1	Rg=10kΩ	-	0.85	1.3	mV	3
3	Output Offset Voltage	Voffset	1	Vin=0	-	0	300	mV	
4	Total Harmonic Distortion	THD	1	PO=1W	-	0.07	0.3	%	
5	Voltage Gain	Gv	1	PO=1W	49.5	51.5	53.5	dB	
6	Maximum Power Output	PO	1	THD=10%	24	30	-	W	
7	Ripple Rejection Ratio	R.R	1	Rg=0 Supply ripple	45	51	-	dB	3,4
8	Standby Current	ISTB	1	Pin 6 OPEN	-	-	3	μA	

Note 3) Measure with DIN/Audio filter.

4) Ripple frequency = 120Hz, 1Vrms.

Eff. Date	Eff. Date	Eff. Date	Eff. Date	
6-SEP-88	30-MAY-95	17-JUL-98		

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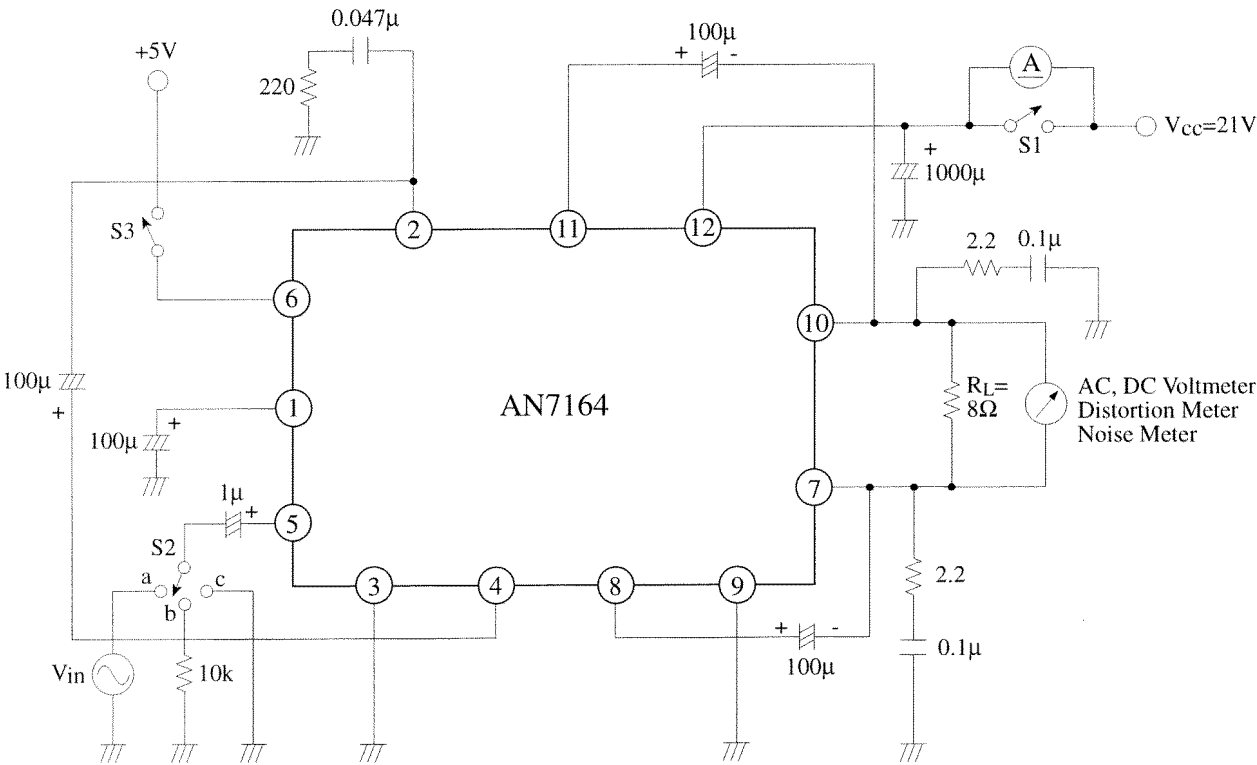
Product Specifications

AN7164

Page No. 3

(Description of test circuit and test method)

Test Circuit 1

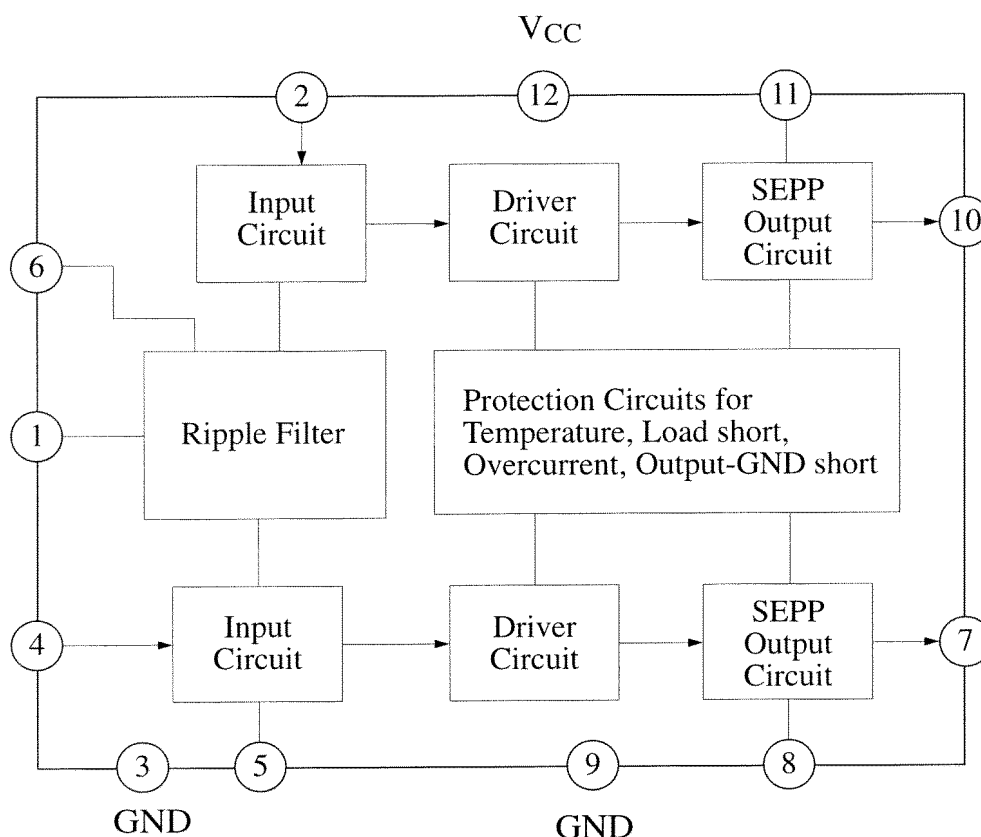


No.		S1	S2	S3
1	IcQ	OFF	c	ON
2	Vno	ON	b	ON
3	Voffset	ON	c	ON
4	THD	ON	a	ON
5	Gv	ON	a	ON
6	Po	ON	a	ON
7	R.R	ON	c	ON
8	IstB	OFF	c	OFF

Note) Pin 6 is a stand-by pin.

Eff. Date	Eff. Date	Eff. Date	Eff. Date
6-SEP-88	30-MAY-95	17-JUL-98	

Circuit Function Block Diagram



Pin Descriptions

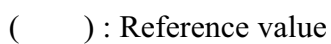
Pin No.	Description	Pin No.	Description
1	Ripple Filter	7	Output (Ch1)
2	Negative Feedback (Ch2)	8	Bootstrap (Ch1)
3	GND (Input)	9	GND (Output)
4	Negative Feedback (Ch1)	10	Output (Ch2)
5	Input	11	Bootstrap (Ch2)
6	Standby / Mute	12	Vcc

Eff. Date	Eff. Date	Eff. Date	Eff. Date	
6-SEP-88	30-MAY-95	17-JUL-98		

Ref No.	E
Total Page	8
Page No.	5

	Package Name	FP12S
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Package Name	FP12S
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Eff. Date	Eff. Date	Eff. Date	Eff. Date	
06-SEP-88	30-MAY-95	17-JUL-98	24-FEB-06	

Prepared	Yiap Shi Hui	Product Specifications (Leadfree) AN7164	Ref No.	F
Checked	John Ng		Total Page	8
Approved	T. Sugimura		Page No.	6A

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EXTERNAL ISSUE

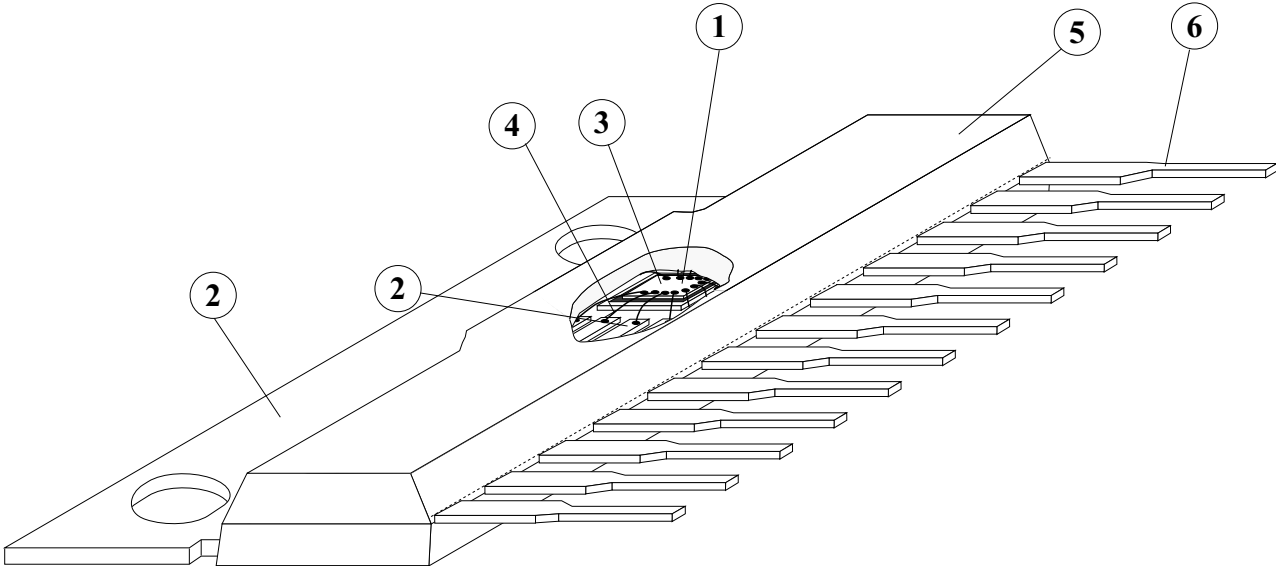
(Structure Description)

Chip surface passivation	SiN,	PSG,	Others ()	①
Lead frame material	Fe group,	Cu group,	Others ()	②, ⑥
Inner lead surface process	Ag plating,	Au plating,	Others ()	②
Outer lead surface process	General Customer: Solder Plating (98Sn-2Bi) SC Buyback: Solder Dip (95.5Sn-2Ag-2Bi-0.5Cu)			⑥
Chip mounting method	Ag paste,	Au-Si alloy,	Solder (95.5Pb-2.5Ag-2Sn)**,	③
Wire bonding method	Thermalsonic bonding,			④
Wire material	Au,	Diameter 38 μm	Others ()	④
Mold material	Epoxy,			⑤
Molding method	Transfer mold,	Multiplunger mold,	Others ()	⑤
Fin material	Cu group,			⑦

*4



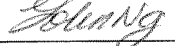
Package FP12S

** Under RoHS exemption clause, Lead (Pb) in high melting temperature type solder (ie. tin-lead solder alloy containing more than 85% of lead), is exempted until 2010.



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Eff. Date	Eff. Date	Eff. Date	Eff. Date
16-DEC-04	24-FEB-06		

Prepared	
Checked	
Approved	

Product Specifications

(Technical Data)

AN7164

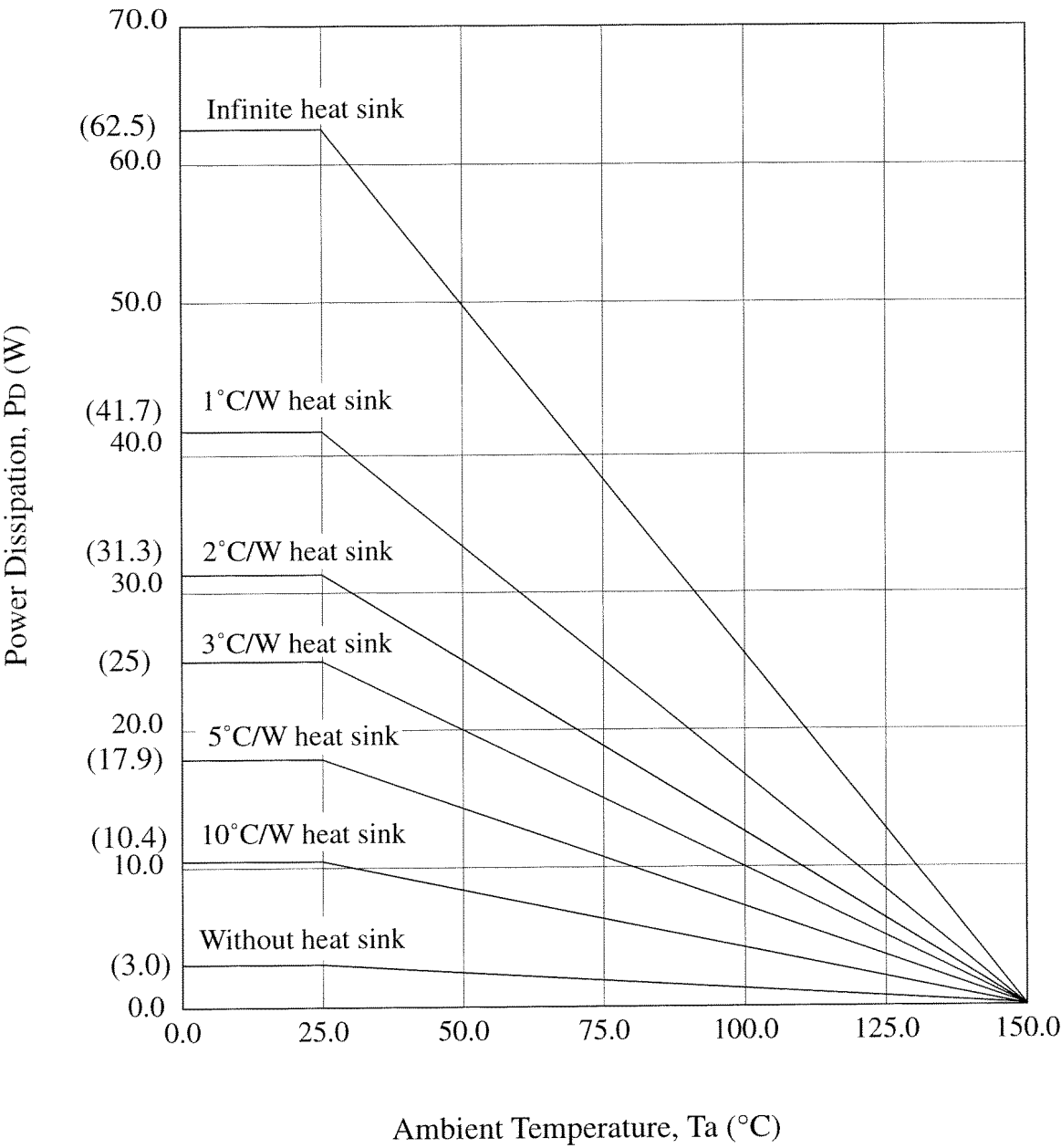
Page No.	7
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FP-12S Package Power Dissipation




Pd - Ta

$R_{th(j-c)} = 2^{\circ}\text{C/W}$

$R_{th(j-a)} = 42^{\circ}\text{C/W}$

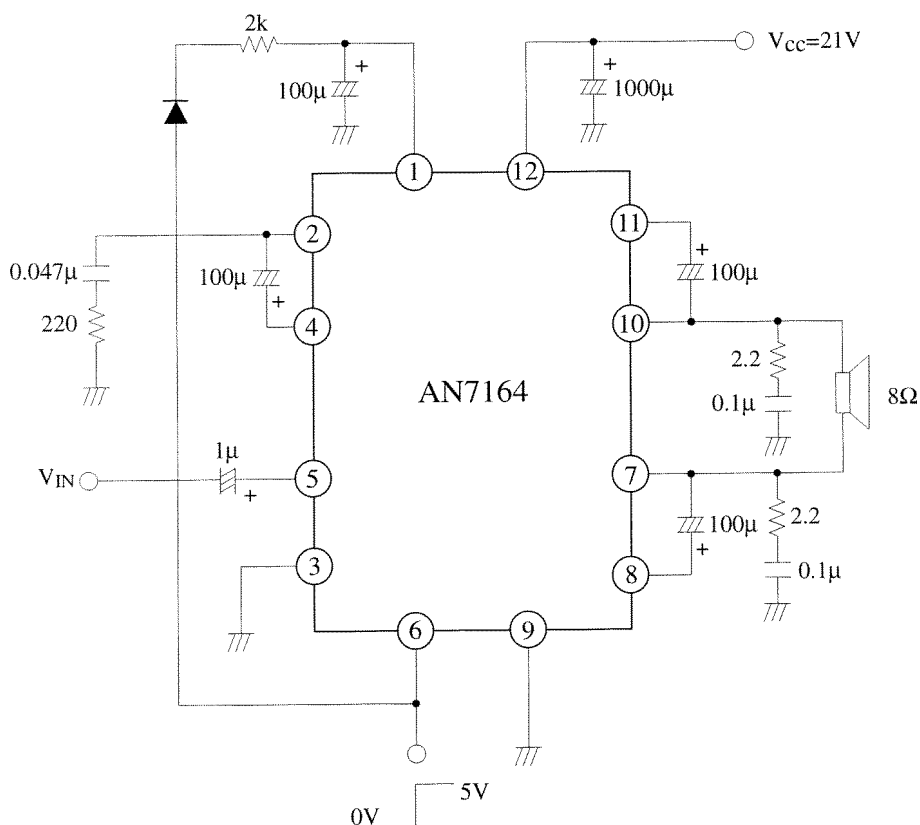


Eff. Date	Eff. Date	Eff. Date	Eff. Date
6-SEP-88	30-MAY-95	17-JUL-98	

Prepared		<div style="text-align: center;"> Product Specifications AN7164 </div>	<div style="border: 2px solid red; padding: 2px; text-align: center;"> APPROVED EXTERNAL ISSUE </div>
Checked			Ref No. G-2 Total Page 8
Approved			Page No. 8

(Precaution)

When standby is OFF (apply 5V at pin 6) at high temperature, the output disappears because ripple filter fast discharge circuit misoperates. It is necessary to force about 1mA of current into pin 1 when standby is OFF.
 Below is one of the example for the application circuit.



Note) Please take note if the external circuit used is by following the test circuit, the standby function may misoperate and IC cannot function.

Eff. Date	Eff. Date	Eff. Date	Eff. Date
6-SEP-88	30-MAY-95	17-JUL-98	